

AMENDMENTS

IN THE CLAIMS

Please amend the claims as follow:

5. (Amended) A method for grinding semiconductor wafers comprising:
- grinding a surface of a semiconductor wafer with fixed abrasive grains and
- without free abrasive grains;
- supplying free abrasive grains to said fixed abrasive grains; and
- subsequently grinding said surface of a semiconductor wafer with said fixed
- abrasive grains and said free abrasive grains.